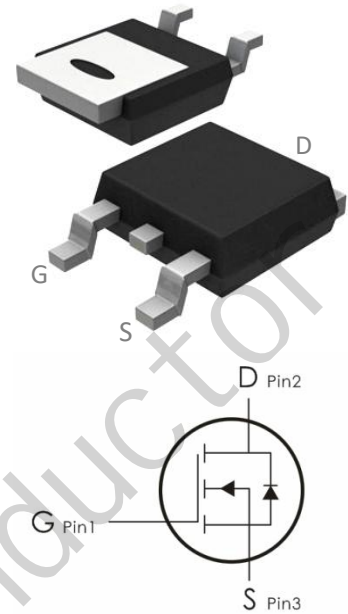


## Description:

This N-Channel MOSFET uses advanced SGT technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.



## Features:

- 1)  $V_{DS}=100V, I_D=55A, R_{DS(ON)} < 12m\ \Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low  $R_{DS(ON)}$ .
- 5) Excellent package for good heat dissipation.

## Absolute Maximum Ratings: ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>1)</sup>	55	A
$I_{D, pulse}$	Pulsed drain current <sup>2)</sup>	165	A
$I_S$	Continuous diode forward current <sup>1)</sup>	55	A
$I_{S, pulse}$	Diode pulsed current <sup>2)</sup>	165	A
$P_D$	Continuous-Source Current <sup>3)</sup>	115	W
$E_{AS}$	Single pulsed avalanche energy <sup>5)</sup>	14	mJ
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.09	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>4)</sup>	62	$^\circ C/W$

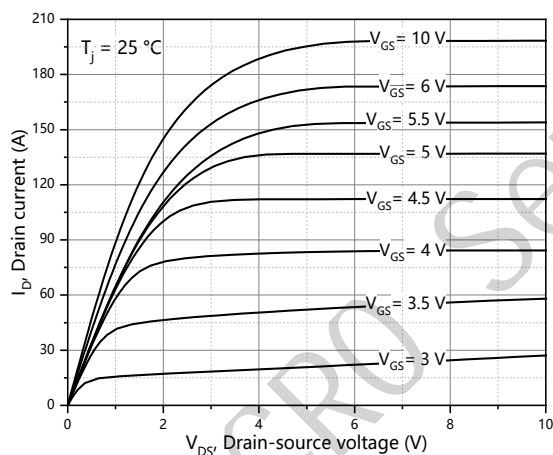
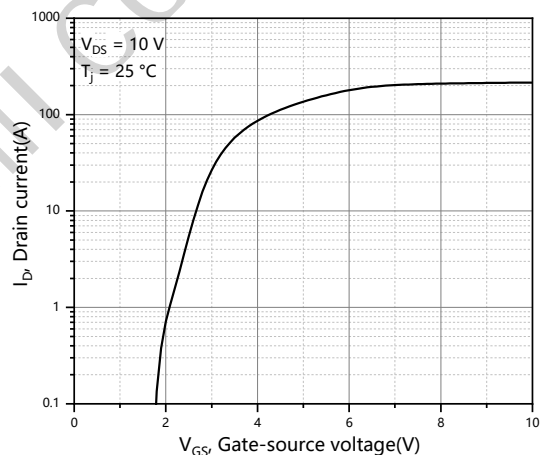
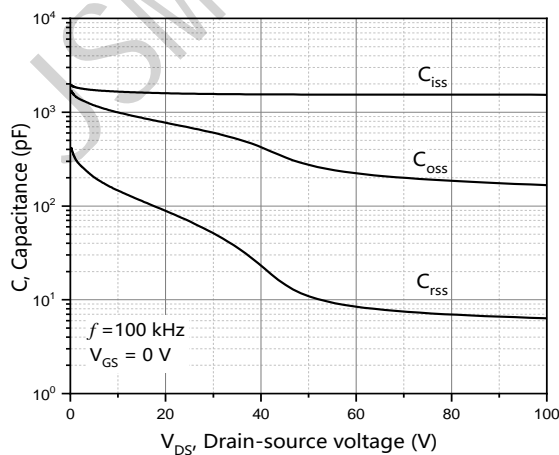
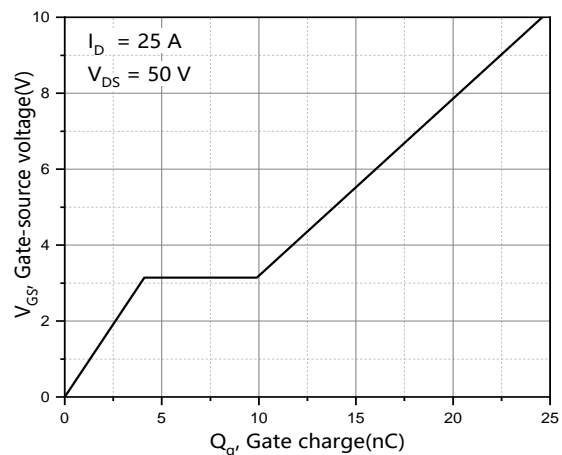
**Electrical Characteristics:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	100	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=100V$	---	---	1	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	$\pm 100$	nA
$R_G$	Gate resistance	$f=1\text{ MHz}$ , Open drain	---	---	3	$\Omega$
<b>On Characteristics</b>						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	1.5	---	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS}=10V, I_D=30A$	---	10	12	m $\Omega$
		$V_{GS}=4.5V, I_D=12A$	---	12	15	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	1550	---	pF
$C_{oss}$	Output Capacitance		---	680	---	
$C_{rss}$	Reverse Transfer Capacitance		---	65	---	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=50V, I_D=25A,$ $V_{GS}=10V, R_G=2\Omega$	---	16	--	ns
$t_r$	Rise Time		---	4	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	35.6	---	ns
$t_f$	Fall Time		---	5.8	---	ns
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V,$ $I_D=25A$	---	24.6	---	nC
$Q_{gs}$	Gate-Source Charge		---	4.1	---	nC
$Q_{gd}$	Gate-Drain "Miller" Charge		---	5.8	---	nC
$V_{plateau}$	Gate plateau voltage		---	3.1	---	V

Drain-Source Diode Characteristics						
<b>V<sub>SD</sub></b>	Source-Drain Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	---	---	1.3	V
<b>trr</b>	Reverse Recovery Time	V <sub>R</sub> =50V, I <sub>S</sub> =25 A  dI <sub>SD</sub> /dt = 100 A/ μ s	---	53.2	---	Ns
<b>qrr</b>	Reverse Recovery Charge			52.5	---	Nc
<b>Irrm</b>	Peak reverse recovery current			1.7	---	A

**Notes:**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=50 V, V<sub>GS</sub>=10 V, L=0.3 mH, starting T<sub>j</sub>=25 °C.

**Typical Characteristics:** (T<sub>C</sub>=25 °C unless otherwise noted)

**Figure 1. Typ. output characteristics**

**Figure 2. Typ. transfer characteristics**

**Figure 3. Typ. capacitances**

**Figure 4. Typ. gate charge**

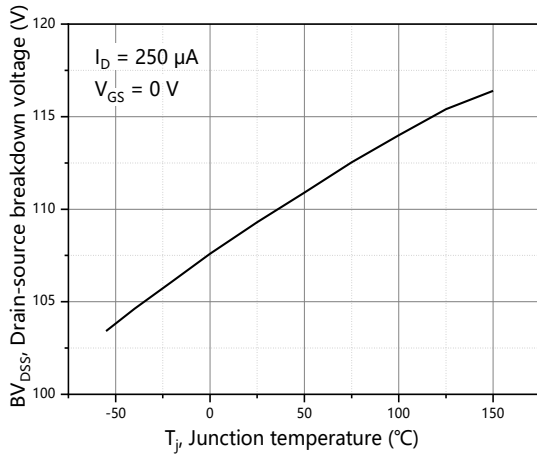


Figure 5. Drain-source breakdown voltage

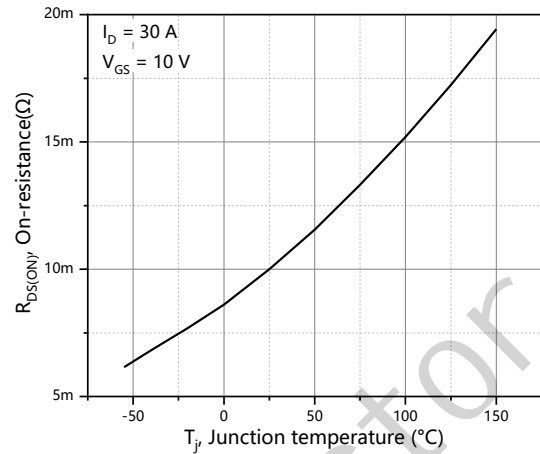


Figure 6. Drain-source on-state resistance

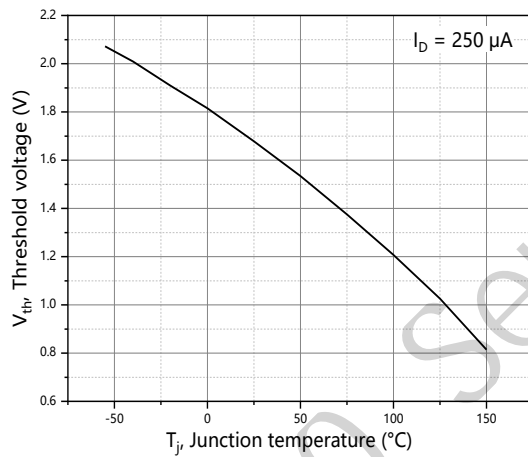


Figure 7. Threshold voltage

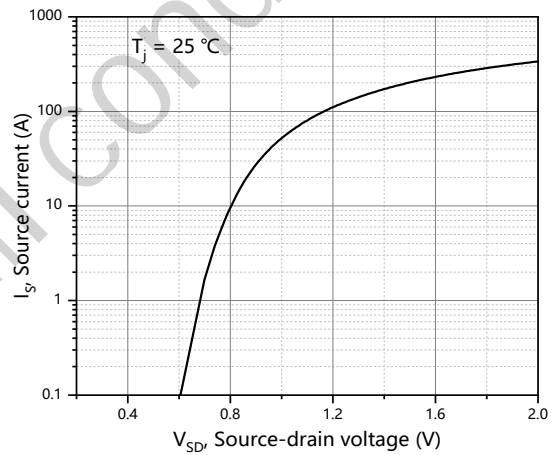


Figure 8. Forward characteristic of body diode

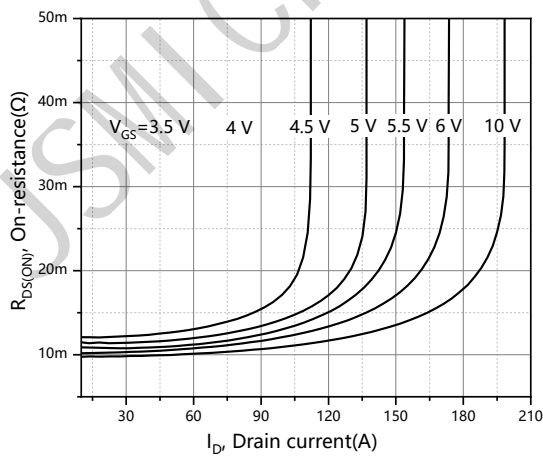


Figure 9. Drain-source on-state resistance

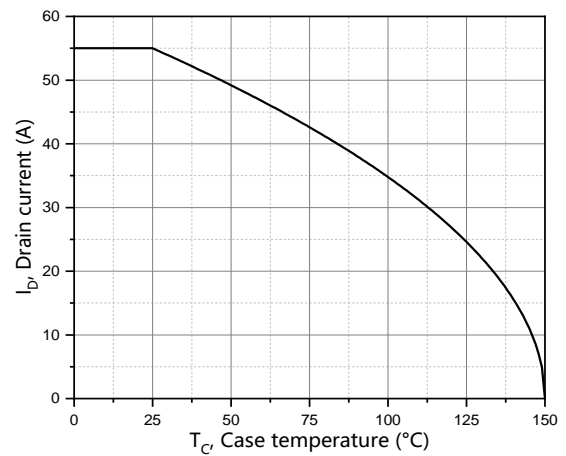


Figure 10. Drain current

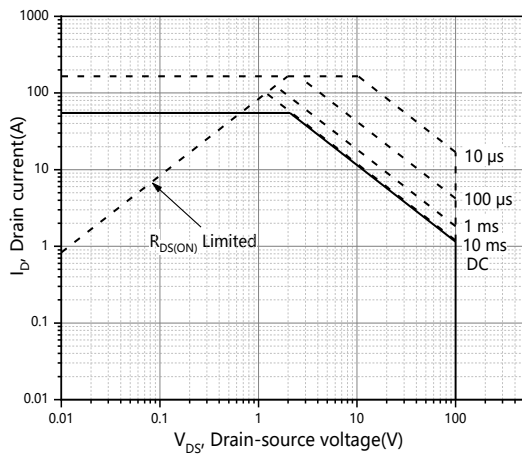


Figure 11. Safe operation area  $T_C=25^\circ\text{C}$

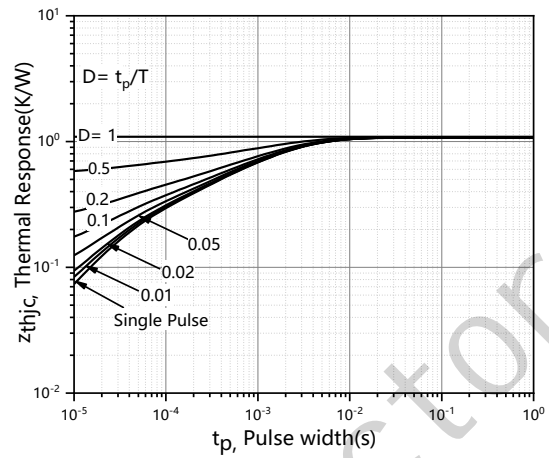
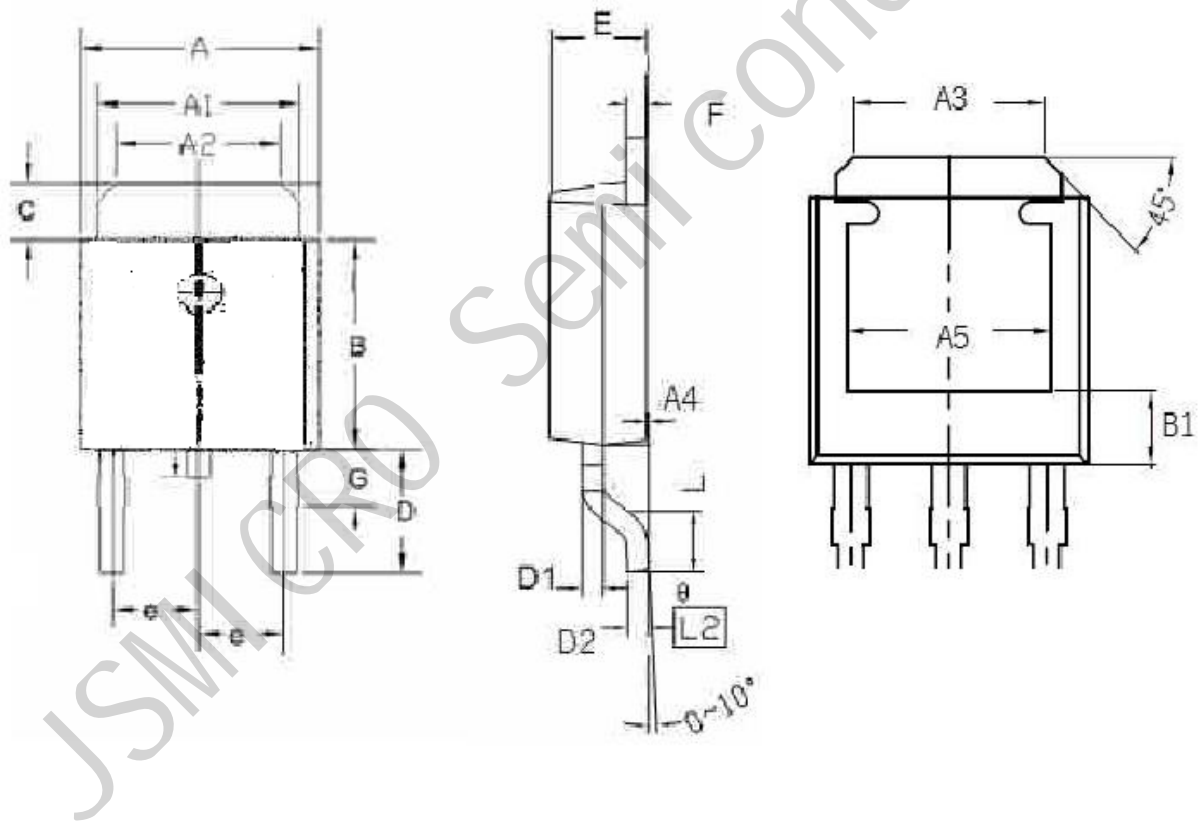


Figure 12. Max transient thermal impedance

### TO-252 Package Dimensions

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	6.40		6.60	D	2.90		3.10
A1	5.20		5.40	D1	0.45		0.55
A2	4.40		4.60	D2	0.45		0.55
A3	4.40		4.60	e		2.30	
A4	0		0.15	E	2.20		2.40
A5	4.65		4.95	F	0.45		0.55
B	5.90		6.20	G		1.70	
B1	1.57		1.77	L	1.40		1.60
C	0.90		0.96	$\theta$ (度)	0		10.00



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